

ABSTRACT

A pressure sensitive adhesive tape for work processing according to the present invention has a substrate, and a pressure sensitive adhesive layer provided on one surface side of the substrate, wherein the pressure sensitive adhesive layer contains a urethane-based resin (A) and an energy ray-curable compound (B), and the energy ray-curable compound (B) is non-reactive with the urethane-based resin (A), has a photopolymerizable unsaturated bond, and has a molecular weight of 35,000 or lower.